

WHAT IS CLAIMED IS:

1. A bonding pad structure comprising:

a first pad; and

at least one second pad coupled with the first pad.

5 2. The bonding pad structure according to claim 1, wherein the first pad is coupled with the second pad by a connecting wire.

3. The bonding pad structure according to claim 1, wherein the arrangement of the corresponding second pad depends on the arrangement of testing probe in IC probing.

10 4. The bonding pad structure according to claim 3, wherein the first pad layout and the second pad layout are arranged in linear.

5. The bonding pad structure according to claim 3, wherein the first pad layout and the second pad layout are arranged in staggered.

15 6. The bonding pad structure according to claim 3, wherein the first pad layout is arranged in staggered and the second pad layout is arranged in linear.

7. The bonding pad structure according to claim 1, wherein the first pad comprises a bump ball.

8. The bonding pad structure according to claim 1 applied to a flip chip.

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